

VERTICAL & EDGE LAUNCH SOLDERLESS COMPRESSION MOUNT

TEST & MEASUREMENT APPLICATIONS

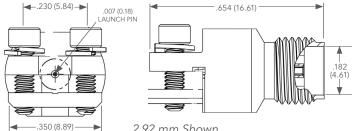


Threaded Coupling | High Mechanical Stability | Field Replaceable | Cost-Effective Assembly



Board thickness = 0.040" to 0.100"

Edge Launch Small Form Factor Improves Density





Vertical **Alignment Features Ensure Repeatable** Peak Connector Performance



Read about this exclusive Samtec technology over on our blog.

DC TO

2.92 mm Shown

BOARD LAUNCH DESIGN SERVICES AVAILABLE

Learn more at: samtec.com/RF or contact: RFGroup@samtec.com

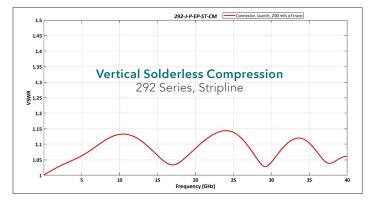
TECHNICAL SPECIFICATIONS

Vertical & Edge Launch Solderless Compression Mount









Measured (2.92 mm, 292 Series - Stripline): The VSWR above used AFR on the measurement from the reference plane of the connector into 0.2" of board trace. Board construction was a straight stripline trace on a 6 layer Tachyon 100G board.

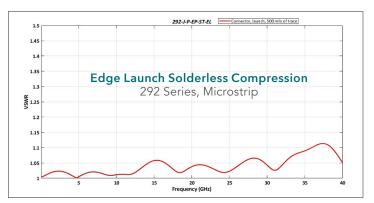
1.35 mm 90 GHz, 50 Ohm Solderless		
135 Series	Vertical	
Board Thickness	0.016" to 0.125"	
Torque (board mount)	0.5 ~ 0.8 in-lbs	

SMPM 65 GHz, 50 Ohm Solderless		
GPPC Series	Vertical	
Board Thickness	0.016" to 0.125"	
Torque (board mount)	0.9 ~ 1.3 in-lbs	

1.85 mm 65 GHz, 50 Ohm Solderless			
185 Series	Vertical	Edge Launch	
Board Thickness	0.016" to 0.125"	0.040" to 0.100"	
Torque (board mount)	0.5 ~ 0.8 in-lbs		

2.40 mm 50 GHz, 50 Ohm Solderless			
240 Series	Vertical	Edge Launch	
Board Thickness	0.016" to 0.125"	0.040" to 0.100"	
Torque (board mount)	0.5 ~ 0.8 in-lbs		

2.92 mm 40 GHz, 50 Ohm Solderless			
292 Series	Vertical	Edge Launch	
Board Thickness	0.016" to 0.125"	0.040" to 0.100"	
Torque (board mount)	0.5 ~ 0.8 in-lbs		



Measured (2.92 mm, 292 Series - Microstrip): The VSWR above used AFR on the measurement from the reference plane of the connector into 0.5" of board trace. Board construction was a straight microstrip trace on a 4 layer stackup with an outer 10 mil core of I-Tera MT40.